# AMD 24-Pin XOR PAL\* Family

24-Pin IMOX<sup>TM</sup> Programmable Array Logic (PAL) Elements

#### **PRELIMINARY**

## DISTINCTIVE CHARACTERISTICS

- AND-OR-XOR logic structure
- AMD's superior IMOX technology
  - Guarantees tpD = 20 ns max
- Individually programmable output polarity on each output
- Eight logical product terms per output
- Programming yields > 98% are realized via platinumsilicide fuse technology and the use of added test words
- Post Programming Functional Yield (PPFY) of 99.9%
- PRELOAD feature permits full logical verification
- Reliability assured through more than 70 billion fuse hours of life testing with no failures
- Full AC and DC parametric testing at the factory through on-board testing circuitry
- > 3000V ESD input protection per pin
- JEDEC-Standard LCC and PLCC pinout

## **GENERAL DESCRIPTION**

AMD 24-pin XOR PAL devices are high-speed, electrically programmable array logic elements. They utilize the familiar sum-of-products (AND-OR-XOR) structure allowing users to program custom logic functions to fit most applications precisely. Typically they are a replacement for low-power Schottky SSI/MSI logic circuits that require an exclusive-OR function, reducing chip count by more than 5 to 1 and greatly simplifying prototyping and board layout.

Five different devices are available, including both registered and combinatorial devices. All devices have user-programmable output polarity on all outputs. A variety of speed options allow the designer maximum flexibility in matching precise system requirements. The Product Selector Guide below shows the available speed options. The second table gives details about the functionality of the five available devices.

Please see the following pages for Block Diagrams.

#### PRODUCT SELECTOR GUIDE

#### AMD PAL Speed/Power Families

	tç ns (l	tp <sub>D</sub> ns (Max.)		ts ns (Min.)		t <sub>CO</sub> ns (Max.)		IOL mA (Min.)	
Family	C Devices	M Devices	C Devices	M Devices	C Devices	M Devices	C/M Devices	C Devices	M Devices
Very High-Speed (-20 & -25) Versions	20	25	20	25	13	15	210	24	12
High-Speed (-30 & -35) Versions	30	35	30	35	15	25	180	24	12
High-Speed, Half-Power (-30L & -35L) Versions	30	35	30	35	15	25	90	24	12
Standard (-40 & -45) Versions	40	45	40	45	30	35	180	24	12
Half-Power (-40L & -45L) Versions	40	45	40	45	30	35	90	24	12

Part Number	Array Inputs			Outputs/Polarity	Package Pins	
22XP10	12 Dedicated, 10 Bidirectional	Ten (2-6)-Wide AND-OR-XOR	Programmable	Bidirectional/Programmable	24	
anyon.	10 Dedicated,	Four (2-6)-Wide AND-OR-XOR	Dedicated	Registered/Programmable	24	
20XRP4	4 Feedback, 6 Bidirectional	Six 8-Wide AND-OR	Programmable Bidirectional/Programmable			
20VDD0	10 Dedicated,	Six (2-6)-Wide AND-OR-XOR	Dedicated	Registered/Programmable	24	
20XRP6	6 Feedback, 4 Bidirectional	Four 8-Wide AND-OR	Programmable	Bidirectional/Programmable	7 2	
207550	10 Dedicated,	Eight (2-6)-Wide AND-OR-XOR	Dedicated	Registered/Programmable	0.4	
20XRP8	8 Feedback, 2 Bidirectional	Two 8-Wide AND-OR	Programmable	Bidirectional/Programmable	24	
20XRP10	10 Dedicated, 10 Feedback	Ten (2-6)-Wide AND-OR-XOR	Dedicated	Registered/Programmable	24	

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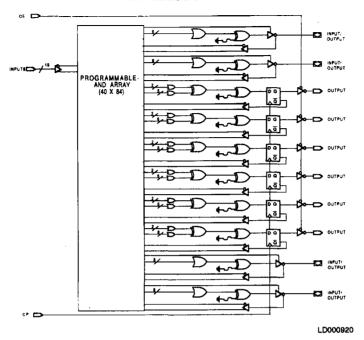
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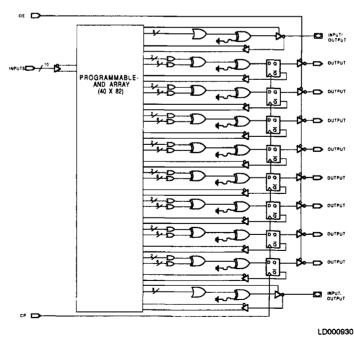
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# BLOCK DIAGRAMS (Cont'd.)

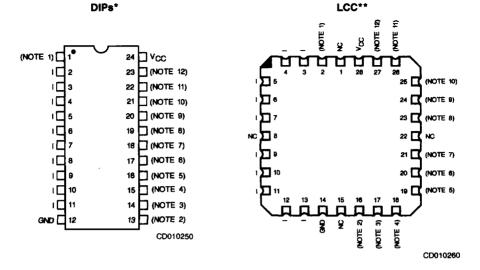
#### AmPAL20XRP6



#### AmPAL20XRP8



# **CONNECTION DIAGRAMS** Top View



Note: Pin 1 is marked for orientation.

Notes:

	22XP10	20XRP4	20XRP6	20XRP8	20XRP10
1	1	CLK	CLK	CLK	CLK
2	-	OE	OE	OE	OE
3	1/0	1/0	1/0	1/0	0
4	1/0	1/0	1/0	0	0
5	1/0	9	0	0	0
6	1/0	0	0	0	0
7	1/0	0	0	0	0
8	1/0	0	0	0	0
9	1/0	0	0	0	0
10	1/0	1/0	0	0	0
11	1/0	1/0	1/0	0	0
12	1/0	1/0	1/0	1/0	0

<sup>\*</sup>Also available in 24-Pin Ceramic Flatpack. Pinouts identical to DIPs.

#### PIN DESIGNATIONS

I = Input

I/O = Input/Output

O = Output

V<sub>CC</sub> = Supply Voltage GND = Ground

CLK = Clock

OE = Output Enable

NC = No Connect

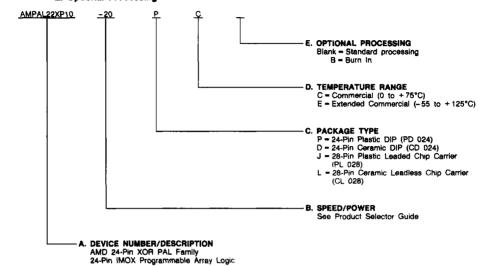
<sup>\*\*</sup>Also available in 28-Pin Plastic Leaded Chip Carrier. Pinouts identical to LCC.

#### ORDERING INFORMATION

#### Standard Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: A. Device Number

- B. Speed Option (if applicable)
- C. Package Type
- D. Temperature Range
- E. Optional Processing



Valid Combinations	
AMPAL22XP10-20/-30/-30L/-40/-40L	
AMPAL20XRP4-20/-30/-30L/-40/-40L	PC, DC,
AMPAL20XRP6-20/-30/-30L/-40/-40L	DCB, DE,
AMPAL20XRP8-20/-30/-30L/-40/-40L	JC, LC, LE
AMPAL20XRP10-20/-30/-30L/-40/-40L	

#### **Valid Combinations**

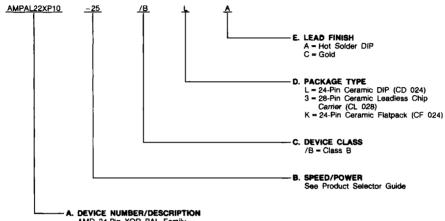
Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released combinations, and to obtain additional data on AMD's standard military grade products.

#### ORDERING INFORMATION (Cont'd.)

#### **APL Products**

AMD products for Aerospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MIL-STD-883C requirements. CPL (Controlled Products List) products are processed in accordance with MIL-STD-883C, but are inherently non-compliant because of package, solderability, or surface treatment exceptions to those specifications. The order number (Valid Combination) for APL products is formed by a combination of: A. Device Number

- B. Speed Option (if applicable)
- C. Device Class
- D. Package Type
- E. Lead Finish



AMD 24-Pin XOR PAL Family 24-Pin IMOX Programmable Array Logic

Valid Combinations	
AMPAL22XP10-25/-35/-35L/-45/-45L	
AMPAL20XRP4-25/-35/-35L/-45/-45L	/BLA.
AMPAL20XRP6-25/-35/-35L/-45/-45L	/B3C,
AMPAL20XRP8-25/-35/-35L/-45/-45L	/BKA
AMPAL20XRP10-25/-35/-35L/-45/-45L	

#### **Valid Combinations**

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations or to check for newly released valid combinations.

#### Group A Tests

Group A tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, & 11

# FUNCTIONAL DESCRIPTION AMD 24-Pin XOR PAL Family Characteristics

All members of the AMD 24-Pin XOR PAL Family have common electrical characteristics and programming procedures. All parts are produced with a fusible link at each input to the AND gate array, and connections may be selectively removed by applying appropriate voltages to the circuit.

Initially the AND gates are connected, via fuses, to both the true and complement of each input. By selective programming of fuses the AND gates may be "connected" to only the true input (by blowing the complement fuse), to only the complement input (by blowing the true fuse), or to neither type of input (by blowing both fuses) establishing a logical "don't care." When both the true and complement fuses are left intact a logical false results on the output of the AND gate, while all fuses blown results in a logical true state. On the AmPAL22XP10 device, the AND gates are connected to fixed (2-6) OR-XOR structures whose outputs become device outputs. The remaining four (registered) devices function as follows: for combinatorial outputs, the AND gates are connected to fixed-OR gates whose outputs become device outputs. For registered outputs, the AND gates are connected to fixed (2-6) OR-XOR structures whose outputs become output register inputs.

All parts are fabricated with AMD's fast programming, highly reliable Platinum-Silicide Fuse technology. Utilizing an easily implemented programming algorithm, these products can be rapidly programmed to any customized pattern. Extra test words are pre-programmed during manufacturing to insure extremely high field programming yields (> 98%), and provide extra test paths to achieve excellent parametric correlation.

#### **Power-Up Reset**

The registered devices in the AMD PAL family have been designed to reset during system power-up. Following power-up, all registers will be initialized to zero, setting all the outputs to a logic 1. This feature provides extra flexibility to the designer and is especially valuable in simplifying state machine initialization.

#### **PRELOAD**

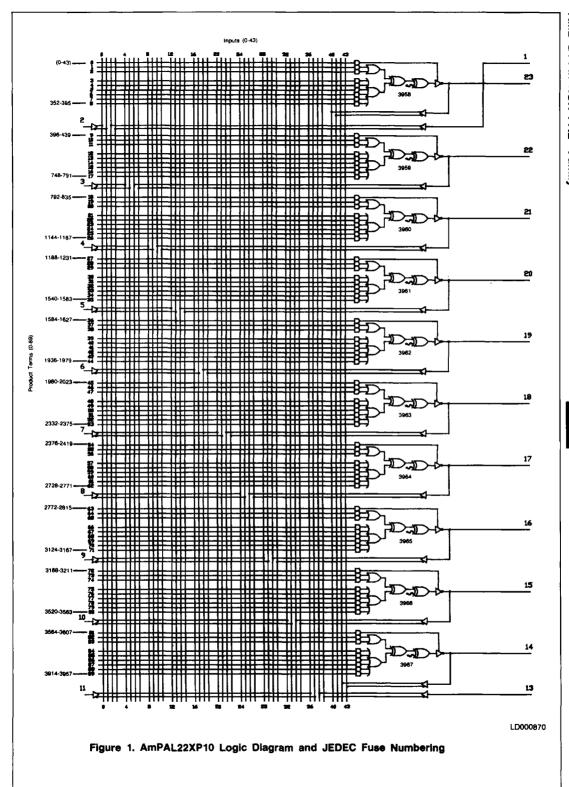
AMD PAL devices are designed with unique PRELOAD circuitry that provides an easy method of testing registered devices for logical functionality. PRELOAD allows any arbitrary state value to be loaded into the registered output of an AMD PAL device.

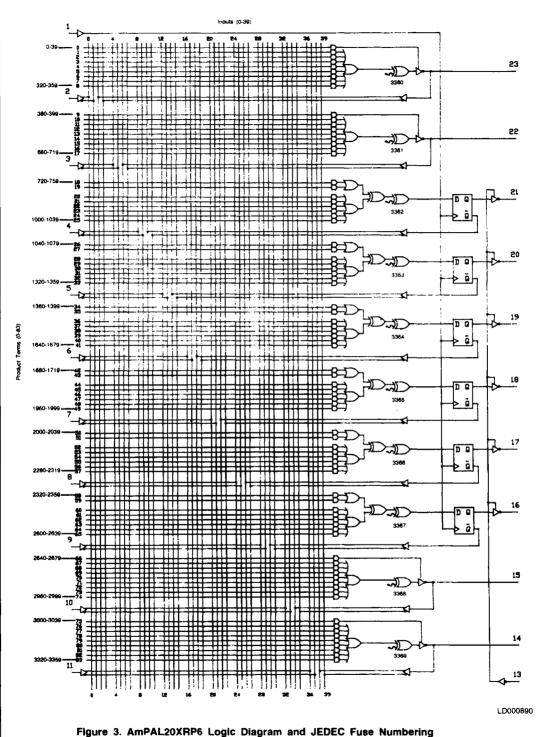
A typical functional test sequence would be to verify all possible state transitions for the device being tested. This requires the ability to set the state registers into an arbitrary "present state" value and to set the device inputs to any arbitrary "present input" value. Once this is done, the state machine is clocked into a new state or "next state." The next state is then checked to validate the transition from the present state. In this way any state transition can be checked.

Without PRELOAD, it is difficult and in some cases impossible to load an arbitrary present state value. This can lead to logic verification sequences that are either incomplete or excessively long. Long test sequences result when the feedback from the state register "interferes" with the inputs, forcing the machine to go through many transitions before it can reach an arbitrary state value. Therefore the test sequence will be mostly state initialization and not actual testing. The test sequence becomes excessively long when a state must be reentered many times to test a wide variety of input combinations.

In addition, complete logic verification may become impossible when states that need to be tested cannot be entered with normal state transitions. For example, even though necessary, the state entered when a machine powers up cannot be tested, because it cannot be entered from the main sequence. Similarly, "forbidden" or don't care states that are not normally entered need to be tested to ensure that they return to the main sequence.

PRELOAD eliminates these problems by providing the capability to go directly to any desired arbitrary state. Thus test sequences may be greatly shortened, and all possible states can be tested, greatly reducing test time and development costs, and guaranteeing proper in-system operation.





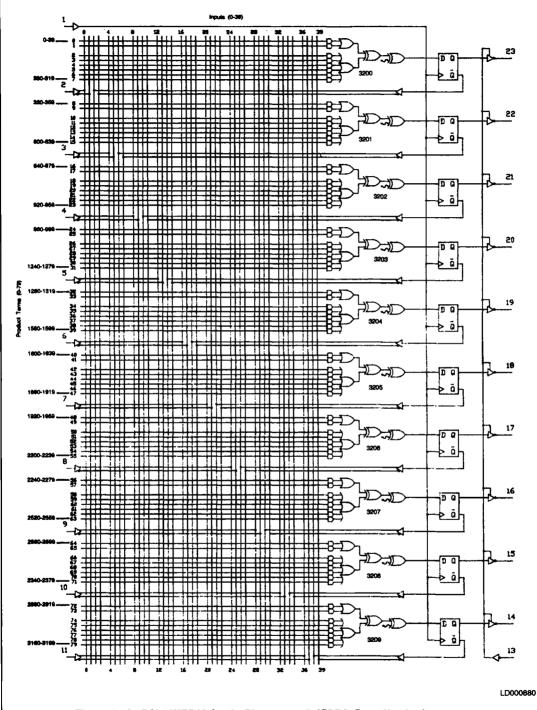


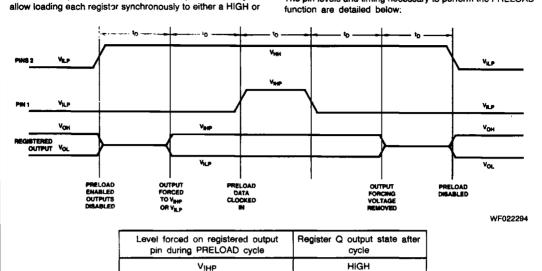
Figure 5. AmPAL20XRP10 Logic Diagram and JEDEC Fuse Numbering

#### **PRELOAD of Registered Outputs**

The AMD 24-pin XOR PAL devices incorporate circuitry to

LOW state. This feature simplifies testing since any initial state for the registers can be set to optimize test sequencing.

The pin levels and timing necessary to perform the PRELOAD function are detailed below:



#### Power-Up Reset

The registered devices in the AMD 24-Pin XOR PAL Family have been designed with the capability to reset during system power-up. Following power-up, all registers will be reset to LOW. The output state will be HIGH. This feature provides flexibility to the designer and is especially valuable in simplifying state-machine initialization. A timing diagram and parameter table are shown below. Due to the asynchronous operation

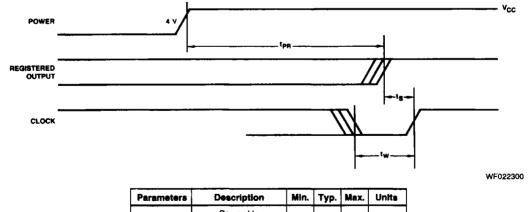
VILP

of the power-up RESET and the wide range of ways V<sub>CC</sub> can rise to its steady state, two conditions are required to ensure a valid power-up RESET. These conditions are:

1. The V<sub>CC</sub> rise must be monotonic.

LOW

2. Following reset, the clock input must not be driven from LOW to HIGH until all applicable input and feedback setup times are met.



Parameters	Description	Min.	Тур.	Max.	Units	
tpR	Power-Up Reset Time	'		1000	ns	
ts			Switchir cteristic			
tw	Clock Width					

### **ABSOLUTE MAXIMUM RATINGS**

Storage Temperature65 to +150°C
Supply Voltage to Ground Potential
(Pin 24 to Pin 12) Continuous0.5 to +7.0 V
DC Voltage Applied to Outputs
(Except During Programming)0.5 V to +V <sub>CC</sub> Max.
DC Voltage Applied to Outputs
During Programming16 V
Output Current Into Outputs During
Programming (Max Duration of 1 sec) 200 mA
DC Input Voltage0.5 to +5.5 V
DC Input Current30 to +5 mA

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

#### **OPERATING RANGES**

Commercial (C) Devices
Temperature (T <sub>A</sub> ) 0 to +75°C
Supply Voltage (V <sub>CC</sub> )+4.75 to +5.25 V
Extended Commercial (E) Devices
Temperature (T <sub>A</sub> )55°C Min.
Temperature (T <sub>C</sub> )+ 125°C Max.
Supply Voltage (V <sub>CC</sub> )+4.50 to +5.50 V
Military (M) Devices*
Temperature (T <sub>A</sub> )55°C Min.
Temperature (T <sub>C</sub> )+ 125°C Max.
Supply Voltage (V <sub>CC</sub> )+4.50 to +5.50 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

\*Military product 100% tested at T<sub>C</sub> = +25°C, +125°C, and -55°C.

#### DC CHARACTERISTICS over operating range unless otherwise specified; included in Group A, Subgroup 1, 2, 3 tests unless otherwise noted

Parameter Symbol	Parameter Description	Test Co	nditions	Min.	Typ (Ng 1)	Max.	Unita
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = Min., V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -3.2 mA COI	2	3		٧
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min., V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = -24 mA CC			0.5	٧
V <sub>IH</sub> (Note 2)	Input HIGH Level	Guaranteed Input Logical HIG Voltage for All Inputs	H	2.0		5.5	٧
V <sub>IL</sub> (Note 2)	Input LOW Level	Guaranteed Input Logical LOV Voltage for All Inputs				0.8	٧
HL	Input LOW Current	VCC = Max., IN = 0.40 V			-20	-100	μΑ
lін	Input HIGH Current	V <sub>CC</sub> = Max., V <sub>IN</sub> = 2.7 V				25	μΑ
1;	Input HIGH Current	V <sub>CC</sub> = Max., V <sub>IN</sub> = 5				1.0	mΑ
Isc	Output Short-Circuit Current	V <sub>CC</sub> = Max., V <sub>OUT</sub> -	9)	~30	-60	-90	mA
lcc	Power Supply Current	Vcc = 1 Roy - 40L	MIL25 -35, -45 -35L, -45L			210 180 90	mA
Vi	Input Clamp Voltage	<sub>CC</sub> = Min.,   -18 mA			-0.9	-1.2	V
ЮZН	Output Leakage rent	= V <sub>IL</sub> = 0.8 V	V <sub>O</sub> = 2.7 V			100	μА
lozi	(Note 4)	VII.	Vo = 0.4 V			-100	~~

= 25°C Notes: 1. Typical limit

to device ground and all overshoots due to system or tester noise are included. The be tested at a time. Duration of the short circuit should not be more than one second. The second is a second to avoid test problems caused by tester ground degradation.

Parameter Symbol	Parameter Description	Test	Test Conditions			
C	Input Capacitance	V <sub>IN</sub> = 2.0 V	Pins 1, 13	11		
CIN	input capacitance	@ f = 1 MHz	Others	6	ρF	
COUT	Output Capacitance	V <sub>OUT</sub> = 2.0 V @ f = 1	MHz	9		

<sup>\*</sup>These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.

#### SWITCHING CHARACTERISTICS over operating range unless otherwise specified: included in Group A Subgroup 9, 10, 11 tests unless otherwise noted COMMERCIAL RANGE

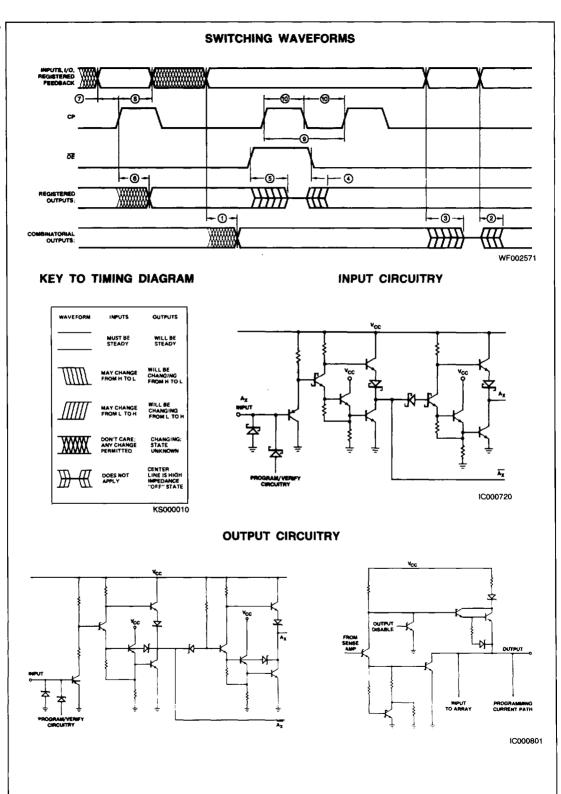
			-20 Version				& -30 ersion	)L		0 & -40 ersions		
No.	Parameter Symbol	Parameter Description	Typ. (Note 1)	Min.	Max.	Typ. (Note 1)	Min.	Max.	Typ. (Note	lin.	Max.	Units
1	t <sub>PD</sub>	Input or Feedback to Non-Registered Output 22XP10, 20XRP4, 20XRP6, 20XRP8			20			30			40	ns
2	t <sub>EA</sub>	Input to Output Enable 22XP10, 20XRP4, 20XRP8, 20XRP8			20			30			10	ns
3	ter	input to Output Disable 22XP10, 20XRP4, 20XRP8, 20XRP8			20			.0			40	ns
4	tpZX	Pin 13 to Output Enable 20XRP4, 20XRP6, 20XRP8, 20XRP10			15			5			35	ns
5	tpxz	Pin 13 to Output Disable 20XRP4, 20XRP6, 20XRP8, 20XRP10			15			Žu			35	ns
6	tco	Clock to Output 20XRP4, 20XRP6, 20XRP8, 20XRP10			13	,					30	ns
7	ts	Input or Feedback Setup Time 20XRP4, 20XRP6, 20XRP8, 20XRP10		20			$\bigvee$			40		ns
8	tн	Hold Time 20XRP4, 20XRP6, 20XRP8, 20XRP10		0						0		ns
9	tp	Clock Period (ts + tco)					47			70		ns
10	tw	Clock Width					15			25		ns
11	fMAX.	Maximum Frequency						22.2			14.3	MHz

Notes: 1. Typical limits are at  $V_{CC} = 5.0$  V and  $T_A = 25^{\circ}C$ . 2. typ is tested with switch  $S_1$  closed and  $C_L = 50$  pF. 3. For three-state outputs, output enable times are tested 1.5 V level; S<sub>1</sub> is open for high impedance to HIGH tested with  $C_L$  = 5 pF. HIGH to high impedance tests mpedance tests are made to the V<sub>OL</sub> + 0.5 V level tests and closed for high impedance to LOW tests. Output are made to an output voltage of VOH - 0.5 V wi with S<sub>1</sub> closed.

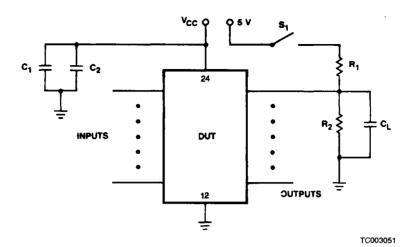
#### MILITARY RANGE

	:		-25 Version		-35 & -35L Version			-45 & -45L Versions				
No.	Parameter Symbol	emeter escription	Typ. (Note 1)	Min.	Max.	Typ. (Note 1)	Min.	Max.	Typ. (Note 1)	Min.	Max.	Units
1	tPD	Input or back ton-Registered Output 2 P4, 20 6, 20XRP8			25			35			45	ns
2	tEA	In tour 10, 20XRP4,			25			35			45	ns
3	ten _	put to Sisable 22XP10, 20XRP4, 0XRP			25			35			45	ns
4	tpzx	Output Zhable 20XRP4, 20XRP8, 20XRP10			20			25			40	ns
5		Pin 1 Lutput Disable 20XRP4, 0XRP6, XRP8, 20XRP10			20			25			40	ns
8		Clock to Output 20XRP4, 20XRP6, 20XRP8, 20XRP10			15			25			35	ns
7	ts	Input or Feedback Setup Time 20XRP4, 20XRP6, 20XRP8, 20XRP10		25			35			45	}	ns
8	tH	Hold Time 20XRP4, 20XRP6, 20XRP8, 20XRP10		0	_		0			0		ns
9	tp:	Clock Period (ts + tco)		40			60			80		ns
10	tw	Clock Width		12			20			30		n\$
11	fMAX.	Maximum Frequency			25			16.7			12.5	MHz

Notes: 1. Typical limits are at V<sub>CC</sub> = 5.0 V and T<sub>A</sub> = 25°C.
2. tp<sub>D</sub> is tested with switch S<sub>1</sub> closed and C<sub>L</sub> = 50 pF.
3. For three-state outputs, output enable times are tested with C<sub>L</sub> = 50 pF to the 1.5 V level; S<sub>1</sub> is open for high impedance to HIGH tests and closed for high impedance to LOW tests. Output disable times are tested with C<sub>L</sub> = 5 pF. HIGH to high impedance tests are made to an output voltage of V<sub>OH</sub> - 0.5 V with S<sub>1</sub> open; LOW to high impedance tests are made to the V<sub>OL</sub> + 0.5 V level with S<sub>1</sub> closed.



# SWITCHING TEST CIRCUIT



Note: C<sub>1</sub> and C<sub>2</sub> are to bypass V<sub>CC</sub> to ground.

TEST OUTPUT LOADS						
Pin Name	Commercial	Military				
R <sub>1</sub>	200 Ω	390 Ω				
R <sub>2</sub>	390 Ω	750 Ω				
C <sub>1</sub>	1 μF	1 μF				
C <sub>2</sub>	0.1 μF	0.1 μF				
CL	50 pF	50 pF				

#### Programming and Verification

AMD 24-Pin XOR PAL Family devices are programmed and verified using AMD's standard programmable logic algorithm. The fuse to be programmed is selected by input line number (array row), product term (array column), and by output (one at a time). The fuse is then programmed and verified by applying a simple sequence of voltages to two control pins (1 and 13).

Input line numbers are addressed using a full decode scheme via TTL levels on pins 6-11 where 6 is the LSB and 11 is the MSB. Even-numbered input lines represent the true version of a signal and odd-numbered lines represent the complement. Input line addressing is shown in Table 1. Note that input line 63 is utilized for selecting the fuses used for programming output polarity.

Product terms are addressed using a 1-of-16 addressing scheme on pins 2-5 where pin 2 is the LSB and 5 is the MSB. Product term addressing is shown in Table 2. Logical and architectural product terms are selected via TTL levels on the four addressing pins.

Fuse selection by output must be done one output at a time (following control pin 1 going to  $V_{HH}$ ), as shown in the programming timing diagram.

Once fuses have been selected, the simple programming and verification sequence may be completed as shown in the programming timing diagram. AC and DC requirements for programming are shown in the programming parameter table.

#### Security Fuse Programming

A single fuse is provided on each device to prevent unauthorized copying of PAL fuse patterns. Once blown, the circuitry enabling fuse verification and registered output PRELOAD is permanently disabled.

Programming of the security fuse is the same as an array fuse. Verification of a blown security fuse is accomplished by verifying the whole fuse array as it every fuse is blown.

#### Programming Yield

AMD PAL devices have been designed to ensure extremely high programming yields ( > 98%). To help ensure that a part was correctly programmed, once programming is completed, the entire fuse array should be verified at both LOW and HIGH VCC. Reverification can be accomplished by reading all ten outputs in parallel rather than one at a time. This verification cycle checks that the array fuses have been blown and can be sensed by the outputs under varying conditions.

AMD PAL devices contain many internal test features, including circuitry and extra fuses which allow AMD to test the ability of each part to perform programming before shipping, to assure high programming yields and correct logical operation for a correctly programmed part. Programming yield losses are most likely due to poor programming socket contact, programming equipment out of calibration, or improper usage of said equipment.

# PROGRAMMING PARAMETERS TA = 25°C

Parameter Symbol		arameter escription	<b>Min.</b>	Тур.	Max.	Units
V <sub>HH</sub>	Control Pin Extra High Level	Pin 1 @ 5-10 mA		11		
*nn	Control Pin Extra High Level	Pin 13 @ 5-10 mA	10	11		
VOP	Program Voltage Pins 14-23 @	15-200 mA	14	15	16	٧
VIHP	Input HIGH Level During Progr	amming and Verify	2.4	5	5.5	٧
VILP	Input LOW Level During Progra	amming and Verify	0.0	0.3	0.5	٧
VCCP	V <sub>CC</sub> During Programming @ I <sub>C</sub>	C = 50-275 mA	5	5.2	5.5	٧
VCCL	V <sub>CC</sub> During First Pass Verifica	tion @ I <sub>CC</sub> = 50-275 mA	4.4	4.5	4.6	٧
Vcch	V <sub>CC</sub> During Second Pass Verif	ication @ ICC = 50-275 mA	5.4	5.5	5.6	٧
VBlown	Successful Blown Fuse Sense	Level @ Output		0.3	0.5	٧
V <sub>OP</sub> /dt	Rate of Output Voltage Chang	e	20		250	V/μ <b>s</b>
dV <sub>13</sub> /dt	Rate of Fusing Enable Voltage	Change (Pin 13 Rising Edge)	100		1000	V/μs
•-	Fusing Time First Attempt	-	40	50	100	μs
t <sub>P</sub>	Subsequent Attempts		4	5	10	ms
to Ot	Delays Between Various Level	Changes	100	200	1000	ns
ty	Period During which Output is	Sensed for VBlown Level			500	ns
VONP	Pull-Up Voltage On Outputs N	ot Being Programmed	V <sub>CCP</sub> - 0.3	VCCP	V <sub>CCP</sub> + 0.3	٧
R	Pull-Up Resistor On Outputs N	lot Being Programmed	1.9	2	2.1	kΩ

# Design Aid Software for AMD 24-Pin XOR PAL Family

Name	Vendor	Versions	Notes
ABEL	Data I/O (206) 881-6444	IBM PC VAX/VMS VAX/UNIX	
CUPL	P-CAD Systems (408) 971-1300	IBM PC VAX/VMS VAX/UNIX CPM 80/86	
AmCUPL	Advanced Micro Devices (408) 732-2400	IBM PC	Supported by P-CAD Systems

# **AMD Qualified Programmers**

Name	Programmer Model(s)	AMD PAL Personality Module	Socket Adapter	
Data I/O	Systems 19, 29	950-1942-0044	303A-011A	
10525 Willow Road N.E. Redmond, WA 93052	60	N/A	Under Development	
Stag Microsystems	Model PPZ	Under Development	0.0.4	
528-5 Weddell Drive Sunnyvale, CA 94086	ZL30	Under Development	On Board	
Valley Data Sciences 2426 Charleston Road Mountain View, CA 94043	160 Series	Under Development	On Board	

## PROGRAMMING TIMING DIAGRAM

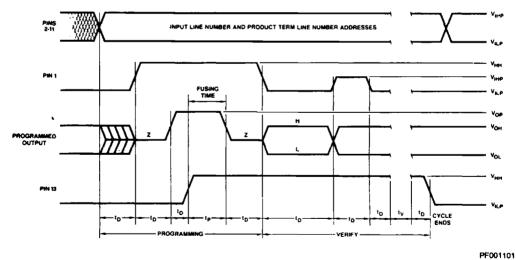
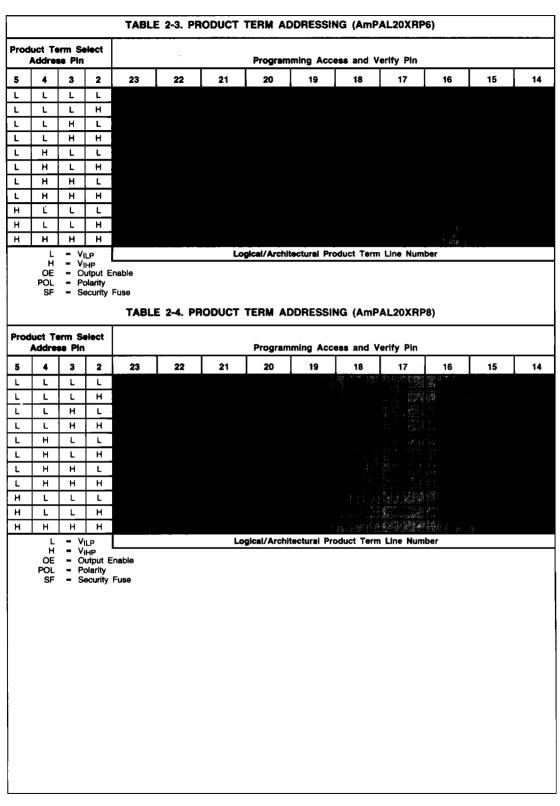


TABLE 1. INPUT ADDRESSING

Input Line	Input Line Number Address Pin States						
Number	6	7	8	9	10	11	
0	L	L	L	L	L	L	
1	L	L	L	L	L	Н	
2	L	L	L	L	Н	L	
3	<u>L</u>	L	L	L	H	H	
4 5	٦	L	L	Н	L	L	
6	L	L	L	H	L		
7	Ľ		L	Н	Н	L	
8	ן נ	L L	Н	[	Ľ	"	
9	[	ן ב	H	٦١	Ĺ	Ь	
10	L	Ĺ	H	L	H	;;	
11	ī	Ĺ	н	Ĺ	н	H	
12	١.	Ĺ	Н	н	L	Ľ	
13	Į į	Ĺ	H	н	Ĺ	H	
14	ΙL	Ĺ	Н	н	H	L	
15	L	L	н	н	Н	H	
16	L	н	L	L	L	L	
17	ΙL	н	L	L	L	н	
18	L	н	L	L	н	L	
19	L	Н	L	L	Н	Н	
20	L	н	L	Н	L	L	
21	L	н	L	Н	L	Н	
22	L	н	L	Н	Н	L	
23	L	н	L	Н	Н	Н	
24	L	н	Н	L	L	L	
25	L	н	Н	L	L	Н	
26	L	H	н	L	Н	L	
27	L	н	Н	L	Н	Н	
28 29	L	H	H	H	L	L	
29 30	<u> </u>	Н			H		
31	L	Н	H	H	Н	L	
32	L   H	L	L	L	L L	L	
33	"	L	L	[	ŗ	Н	
34	'''	L	L	ו	Н	Ĺ	
35	;;	Ĺ	Ĺ	L	н	Н	
36	Ιй	Ĺ	Ĺ	H	L	L	
37	H	ũ	Ē	н	Ē	H	
38	H	L	Ĺ	н	H	L	
39	н	Ĺ	L	н	н	H	
40*	н	L	н	L	L	L	
41*	н	L	н	L	L	Н	
42*	н	Ł	н	L	н	L	
43*	н	L	н	L	н	H	
63**	н	Ħ	H	н	Ŧ	Η	

<sup>\*</sup> Used for AmPAL22XP10 only
\*\* Used for programming polarity
L = V<sub>ILP</sub>
H = V<sub>IHP</sub>



	uct Te Addres	rm Se ss Pin					Program	nming Acc	ess and V	erify Pin			
5	4	3	2	23	22	21	20	19	18	17	16	15	1
Ł	L	L	L		•		•						
L	L	Ļ	Н										
L	L	I	L										
L	L	Н	Н										
L	Н	L	L_										
L	H	Н	H										
ī	н	н	Н										
Н	L	L	L										
Н	L	L	Н										
Н	Н	Н	Н										
	H	- V <sub>I</sub>	LP			Lo	ogical/Archi	tectural Pr	oduct Term	Line Num	ber		
	OE	- 0	HP utput E	nable									
	POL	= Pc	olarity										
	SF	- Se	ecurity	Fuse									
									·				
									·				
									·				